



Component Construction

Photodetector and infrared emitter components are available in plastic or metal packages.

Plastic devices mostly include a lens to improve radiant sensitivity or radiant intensity. Detector chips are mounted on flat leadframe surfaces while leadframes for emitters have a silver plated reflector performing higher radiant intensity.

Devices in metal packages are hermetically sealed, are released for extended operating temperature range and have small optical and mechanical tolerances.

Datasheets of each respective product have to be used to determine polarity.

